Please replace the paragraph beginning on page 11, line 1 with the following rewritten paragraph:

As described above, the property of the polishing surface 12a can be monitored as shown in FIG. 4, while the polishing surface 12a is being dressed. Therefore, the two-dimensional distribution of the absolute amount of material of the polishing surface 12a which has been worn off can be related to polishing conditions or dressing conditions. Accordingly, the polishing conditions including top ring operation, and the dressing conditions can be optimized in a short time.

Please replace the paragraph beginning on page 11, line 10 with the following rewritten paragraph:

An actual process of measuring the polishing surface 12a will be described below. In this example, the sensor 13 is moved at a speed ranging from 10 to 200 mm/sec. The sensor 13 is mounted on the dresser head 11a, and the sensor 13 is moved along the polishing surface 12a on the turntable 12 in accordance with movement of the dresser head 11a. Thus, irregularities or undulations of the polishing surface 12a are converted into an electrical signal. The inventors have concluded form the viewpoint of experimental facilities that the speed of about 100 mm/sec of the sensor 13 is a maximum speed with allowable accuracy of the data.

Please replace the paragraph beginning on page 11, line 21 with the following rewritten paragraph:

The sensor 13 is moved along the polishing surface 12a at the above speed and measures the property of the polishing surface 12a. Irregularities or undulations of the polishing surface 12a are not measured at all points where the sensor 13 is moved. The measured signals from the sensor 13 are sampled every 4 milliseconds. For example, five sampling signals may be averaged to produce data representing a typical property of the polishing surface 12a in the vicinity of the sampling points. Alternatively, each of sampling signals may directly be used to represent the property of the polishing surface 12a.